



## UT3401

Power MOSFET

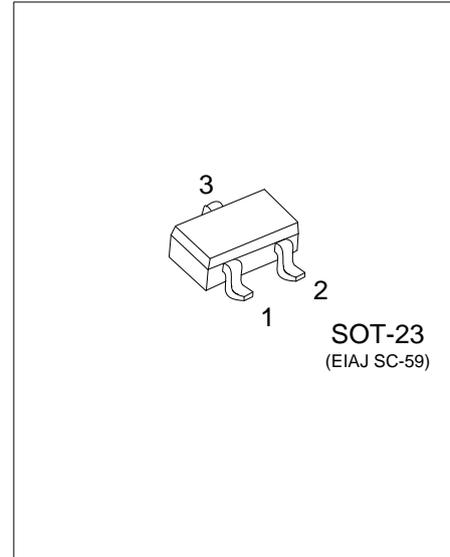
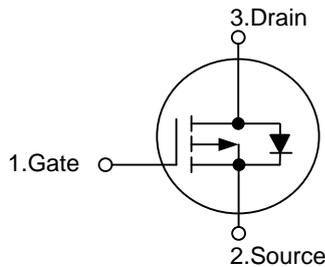
### P-CHANNEL ENHANCEMENT MODE

#### DESCRIPTION

The UTC **UT3401** is P-channel enhancement mode Power MOSFET, designed with high density cell, with fast switching speed, low on-resistance, excellent thermal and electrical capabilities and operation with low gate voltages.

This device is suitable for use as a load switch or in PWM applications.

#### SYMBOL



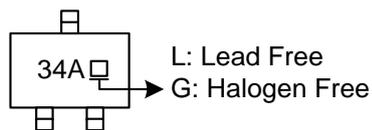
#### ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UT3401L-AE3-R	UT3401G-AE3-R	SOT-23	G	S	D	Tape Reel

Note: Pin Assignment: G: Gate S: Source D: Drain

<p>UT3401G-AE3-R</p> <p>(1) Packing Type</p> <p>(2) Package Type</p> <p>(3) Green Package</p>	<p>(1) R: Tape Reel</p> <p>(2) AE3: SOT-23</p> <p>(3) G: Halogen Free and Lead Free, L: Lead Free</p>
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#### MARKING



## ■ ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V <sub>DSS</sub>	-30	V
Gate-Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note 1)	I <sub>D</sub>	-4.2	A
Pulsed Drain Current (Note 2)	I <sub>DM</sub>	-30	A
Power Dissipation (Note 1)	P <sub>D</sub>	1.25	W
Junction Temperature	T <sub>J</sub>	+150	°C
Storage Temperature	T <sub>STG</sub>	-55 ~ +150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## ■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction-to-Ambient	θ <sub>JA</sub>	100	°C/W

Notes: Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C.

## ■ ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C, unless otherwise specified)

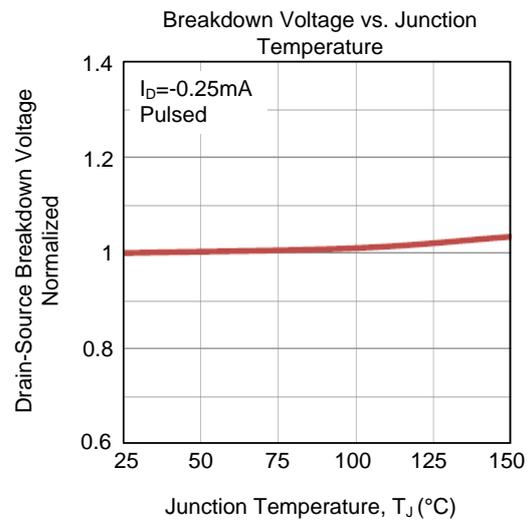
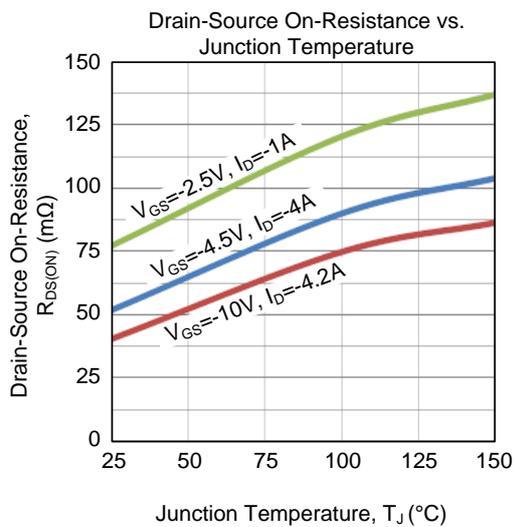
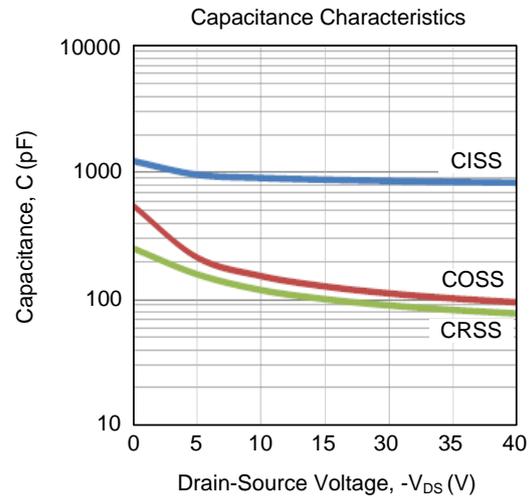
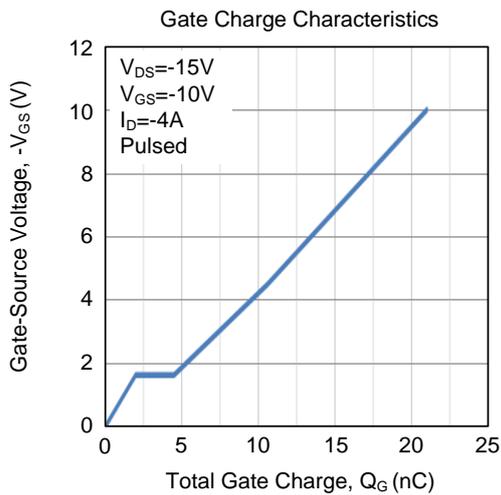
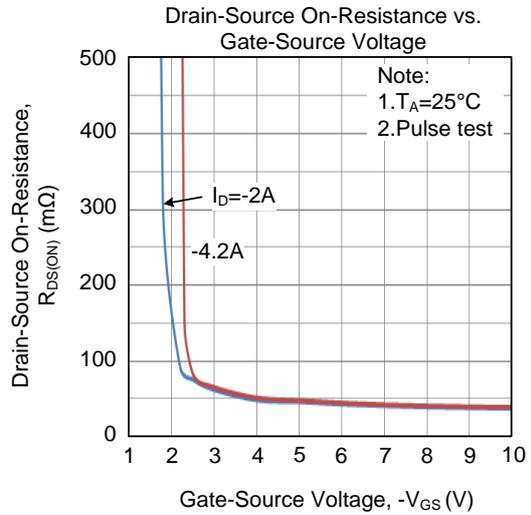
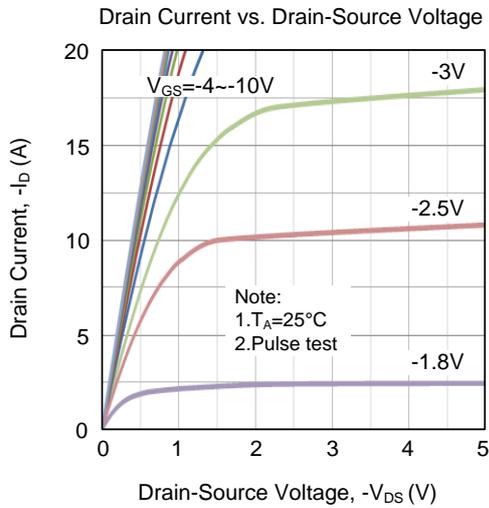
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-30			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V			-1	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.7	-1	-1.3	V
Drain-Source On-State Resistance (Note 2)	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.2A		42	50	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A		53	65	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1A		80	120	mΩ
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, f=1MHz		875		pF
Output Capacitance	C <sub>OSS</sub>			125		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			100		pF
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge (Note 2)	Q <sub>G</sub>	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-15V, I <sub>D</sub> =-4A		10.6		nC
Gate-Source Charge	Q <sub>GS</sub>			2		nC
Gate-Drain Charge	Q <sub>GD</sub>			2.5		nC
Turn-ON Delay Time (Note 2)	t <sub>D(ON)</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V R <sub>L</sub> =3.6Ω, R <sub>G</sub> =6Ω		1.6		ns
Turn-ON Rise Time	t <sub>R</sub>			16		ns
Turn-OFF Delay Time	t <sub>D(OFF)</sub>			38		ns
Turn-OFF Fall Time	t <sub>F</sub>			24		ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				-2.2	A
Drain-Source Diode Forward Voltage (Note2)	V <sub>SD</sub>	V <sub>DS</sub> =0V, I <sub>S</sub> =-1A		-0.75	-1	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =-4A, dI/dt=100A/μs		20.2		ns
Reverse Recovery Charge	Q <sub>rr</sub>				11.2	

Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature.

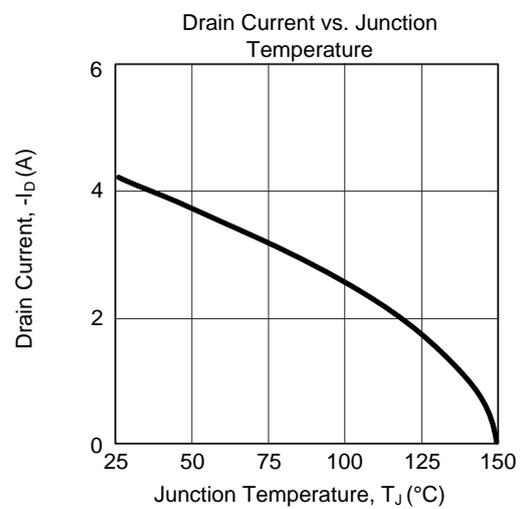
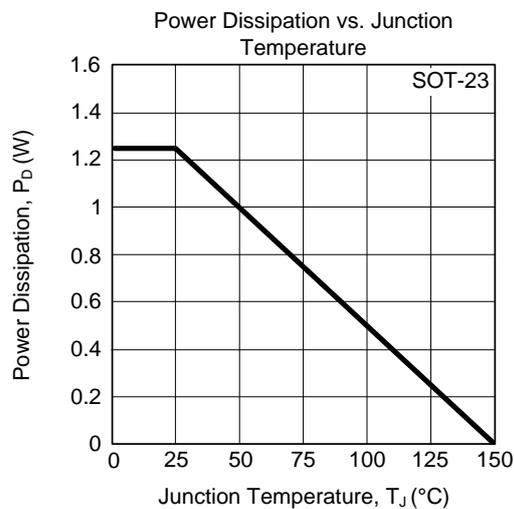
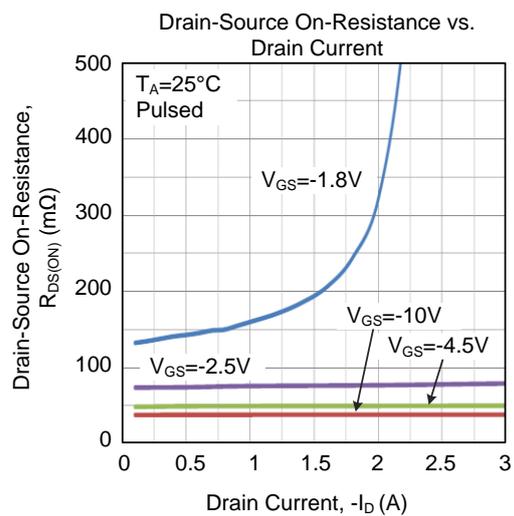
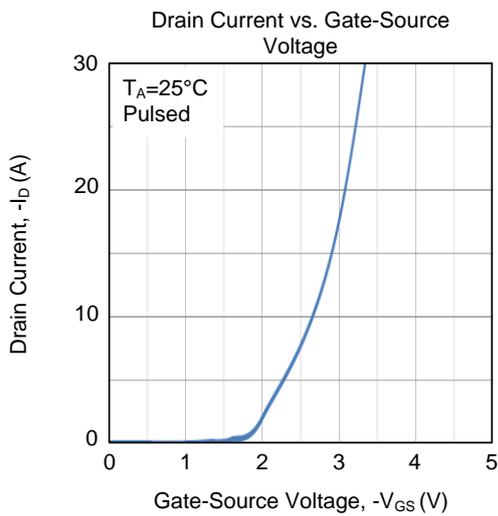
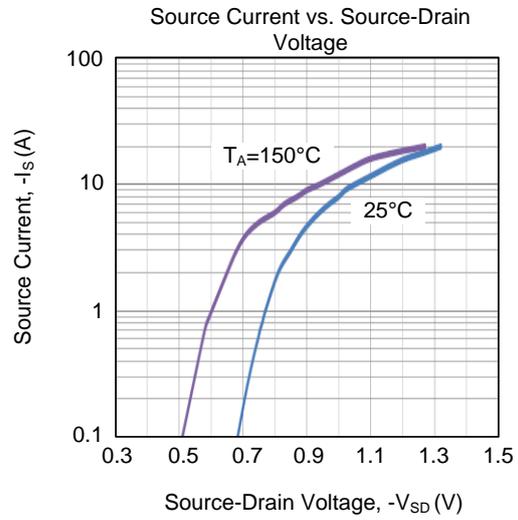
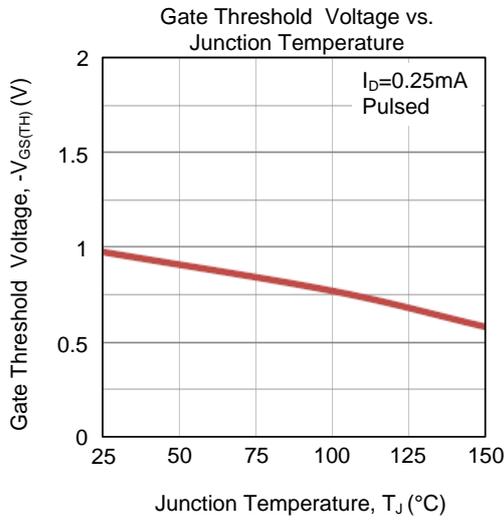
2. Pulse width ≤300μs, duty cycle ≤2%.

3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C.

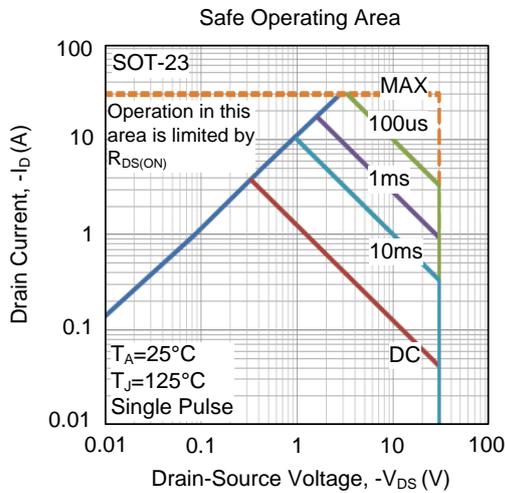
## TYPICAL CHARACTERISTICS



## ■ TYPICAL CHARACTERISTICS (Cont.)



■ **TYPICAL CHARACTERISTICS (Cont.)**



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